

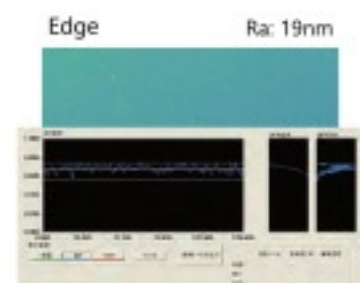
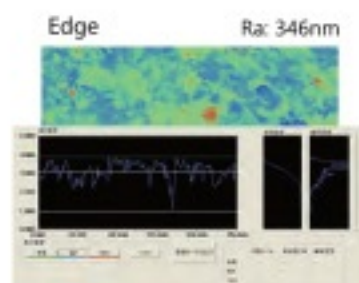
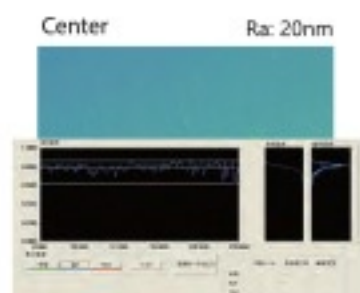
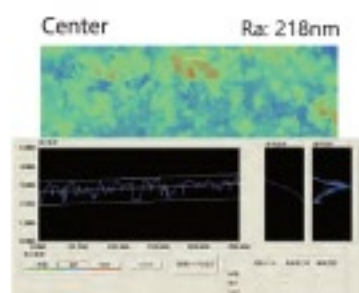
SAPPHIRE GRINDING PERFORMANCE



GENERAL PROCESSING CONDITION

After Coarse Grinding
(Vitrified #325)
Feed 200um/min

After Fine Grinding
(Vitrified #2000)
Feed 30um/min



High self-sharpening, non-dressing

Traditional sapphire wafer grinding process requires frequent dressing, and it needs to do dressing with every single wafer. However, our special vitrified bonded grinding wheel can continue grinding without any dressing during processing.

Able to grind the wafer at very high speed feed rate

High performance of wheel sharpness will be realized. Our SD 270VT / SD 325 VT wheel can feed 200um/min and it can reduce much processing time.

Lower grinding ratio

With our special bond recipe, the grinding ratio of SD270VT and SD325VT is reduced by 10% and the grinding wheels have better wear resistance. Machine idling time and grinding process cost will be decreased.

Customized grinding wheels for any application

The high torque of spindle and rigidity of equipment for the grinding of sapphire wafer are generally required, so it is necessary to choose appropriate bond for each type of machine. We are able to offer the most appropriate grinding wheel for your machine and processing. We have 3w/4w/5w and long chip type for improving wear resistance. You can choose the most suitable spec wheel from our wide selection of specifications.